Listing of All Claims Including Current Amendments

1. (currently amended) Image pick-up module, comprising:

an endoscope shaft having a longitudinal axis;

an electronic image sensor having an image pick-up surface transverse to the longitudinal axis of said shaft;

a single-piece circuit board which is electrically bonded to said image sensor, said circuit board having at least three sections integrally connected with one another, with a first section and a second section ~~extending in spaced relation one to the other~~ extend substantially in parallel one to the other and obliquely or crosswise to said image pick-up surface of said image sensor and a third section being arranged between the first and the second sections, wherein said third section has a substantially V-shaped configuration, said circuit board being folded from a planar board blank comprising at least said integrally formed first, second, and third sections, said third section of said blank being arranged between said first and second sections of said blank,

at least one cable electrically bonded to said circuit board and leading away from said circuit board;

wherein said image sensor is arranged on one end of said circuit board opposite said third section.

2. (cancelled)

3. (cancelled)

4. (currently amended) The image pick-up module of Claim ~~3~~ 1, wherein two legs of said V-shaped third section extend along a straight-line prolongation of said first and said second sections, respectively.

5. (cancelled)

6. (withdrawn) The image pick-up module of Claim 1, wherein said third section is curved.

7. (withdrawn) The image pick-up module of Claim 1, wherein said at least one cable is bonded to an inner surface of the circuit board.

8. (original) The image pick-up module of Claim 1, wherein said at least one cable is bonded to an outer surface of said circuit board.

9. (cancelled).

10. (withdrawn) The image pick-up module of Claim 1, wherein said third section comprises at least one passage for said at least one cable leading away from said circuit board.

11. (withdrawn) The image pick-up module of Claim 10, wherein said at least one passage is configured as a marginal recess in said third section.

12. (withdrawn) The image pick-up module of Claim 1, wherein said third section comprises at least one passage for said at least one cable leading away from said circuit board, wherein said at least one passage is configured as a substantially central opening in said third section.

13. (original) The image pick-up module of Claim 1, wherein an interior of said circuit board, defined by said first, second and third sections, is filled with an electrically non-conductive feeling compound.

14. (original) The image pick-up module of Claim 1, wherein said circuit board comprises a forth section arranged opposite said third section and accommodating said image sensor on its outer surface.

15. (original) The image pick-up module of Claim 13, wherein said forth section comprises at least one of an electric component and at least one electric circuit-board conductor.

16. (withdrawn) The image pick-up module of Claim 1, wherein said circuit board comprises, in addition to said first section and said second section, at least one additional section arranged on one longitudinal side of said circuit board.

17. (original) The image pick-up module of Claim 1, wherein said circuit board is provided on its outer surface with recesses for bonding of said image sensor.

18. (original) The image pick-up module of Claim 1, wherein said third section of said circuit board comprises at least one contact for bonding said cable leading away from said circuit board.

19. (original) The image pick-up module of Claim 1, wherein said third section of said circuit board comprises at least one electric circuit-board conductor for electrically connecting said first section and said second section.

20. (cancelled).

21. (previously presented) The image pick-up module of Claim 1, wherein said first section and said second section of said board blank are flexibly connected via an additional section, but are arranged in spaced relationship at one and the same level, wherein said first section and said second section each serve for bonding said at least one cable, and wherein said third section is flexibly connected to said additional section on an end face of said additional section.

22. (currently amended) A method for assembling an image pick-up module in an endoscope shaft having a longitudinal axis, comprising the steps of:

electrically bonding an electronic image sensor having an image pick-up surface to a single-piece circuit board;

electrically bonding at least one cable leading away from said circuit board to said circuit board;

wherein said circuit board initially has the form of a planar board blank comprising at least three sections integrally connected with one another that can be folded along flexible connecting sections, wherein said at least one cable is bonded to said board blank, wherein said board blank is then folded in such a way that a third section has a substantially V-shaped configuration and is located between a first section and a second section, wherein said first and said second sections extend substantially in parallel one to the other, and wherein said image sensor is bonded to said circuit board at an end of said board opposite said third section such that said image pick-up surface is transverse to the longitudinal axis of the endoscope shaft.

23. (previously presented) The method of claim 22, wherein after bonding of said at least one cable an interior of said circuit board is filled up with a curing electrically non-conductive filling compound.

24. (currently amended) Image pick-up module, comprising:

an endoscope shaft having a longitudinal axis;

an electronic image sensor including an image pick-up surface transverse to the longitudinal axis of said shaft;

a circuit board electrically bonded to said image sensor, said circuit board comprising

first and second sections, said first and second sections each having a first end bonded to said image sensor and a second end, wherein said first and second sections extend longitudinally from said image sensor substantially perpendicular to the image pick-up surface of said sensor and substantially in parallel to ~~each~~ one other; and

a third section having a substantially V-shaped configuration integrally formed with the second end of said second section;

at least one cable electrically bonded to said circuit board and leading away from said circuit board.

25. (cancelled)